

## Product Advisory

Issue Date: 2-Jun-2022

**Change Description:**

Add substrate 2<sup>nd</sup> source for BCM5720

**Parts Affected:**

BCM5720AOKFBG  
BCM5720AOKFBG2  
BCM5720LA0KPBG

**Description and Extent of Change:**

Add Fastprint as an additional substrate supplier for the above device(s). The extent of the change is minimal. Substrate design is the same, only the vendor is different. Fastprint is in mass production for the above package technology.

Current	To Be
UMTC	1 <sup>st</sup> source: UMTC 2 <sup>nd</sup> source: Fastprint

**Reasons for Change:**

Manufacturing flexibility and better substrate lead time.

**Effect of Change on Fit, Form, Function, Quality, or Reliability:**

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed to ensure normal parametric distribution, consistent electrical performance, and reliability.

**Effective Date of Change:**

Product shipments using this change will begin after **15-Jul-2022**. Timing of shipment of the changed part will vary by part number depending on customer demand and inventory levels.

**Qualification Data:**

Stress Test	Condition	Read Points	Sample Size (ss)	Requirements	Results (#fails/ss)
		Cycles / Hrs.			
Precondition	MSL3	192hrs	154	0 failures	0 / 154
	JESD22-A113E				
Temp Cycle	-55°C / 125°C	700 cycles	77	0 failures	0 / 77
	JEDEC Std 22-A104-C Cond. B				
Unbiased HAST	130°C, 85% RH	96hrs	77	0 failures	0 / 77
	JEDEC Std 22-A118				
HTSL	TA=150°C	1000hrs	77	0 failures	0 / 77

**Software / Firmware Update:**

As with all changes, please check with your Broadcom FAE to determine if any software or firmware updates are required as a result of this change.